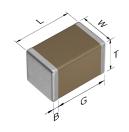
积层贴片陶瓷片式电容器

C2012JB1H154K085AA

RoHS Reach Halogen Free Pb Free

交货型号	C2012JB1H154KT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1.25mm ±0.20mm	
厚度(T)	$0.85 \text{mm} \pm 0.15 \text{mm}$	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
推存序益型/PJ (FA)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
1世行。序血和/p (t D)	0.70mm to 0.90mm (Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
3世行が土血(中)四 は U/	0.90mm to 1.20mm(Reflow Soldering)	

电·	气特性
电容	$150 nF \pm 10\%$
额定电压	50VDC
温度特性	JB(±10%)
耗散因数(Max.)	2. 5%
绝缘电阻 (Min.)	3333М Ω

	其他	
₩EL+2×->>-+	流体	
焊接方法	回流	
AEC-Q200	NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.



RoHS Reach Halogen Free Pb Free



特性图表(这是参考数据,并不保证产品的特性。)

[!] Images are for reference only and show exemplary products.

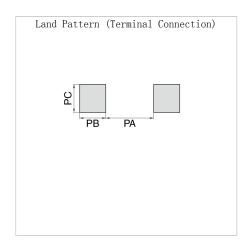
[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

RoHS Reach Halogen Free Pb Free



Associated Images



[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.